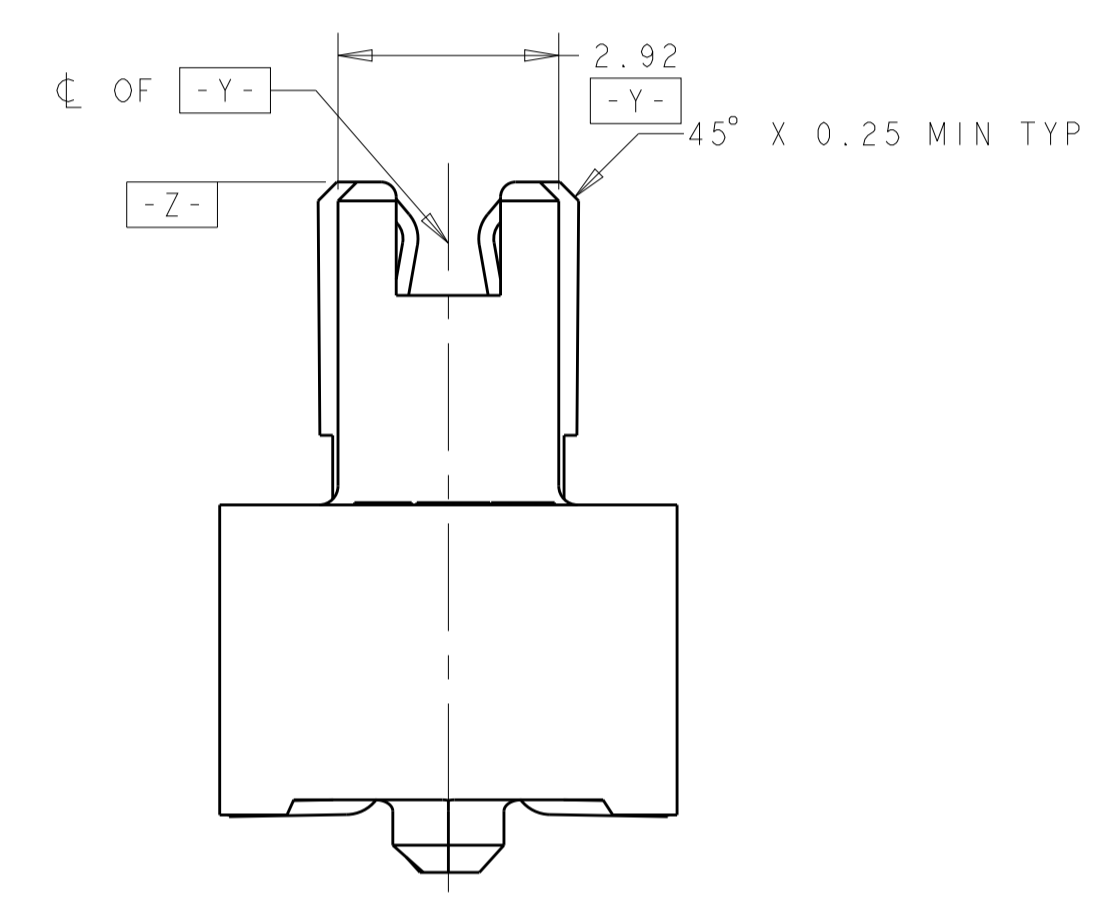
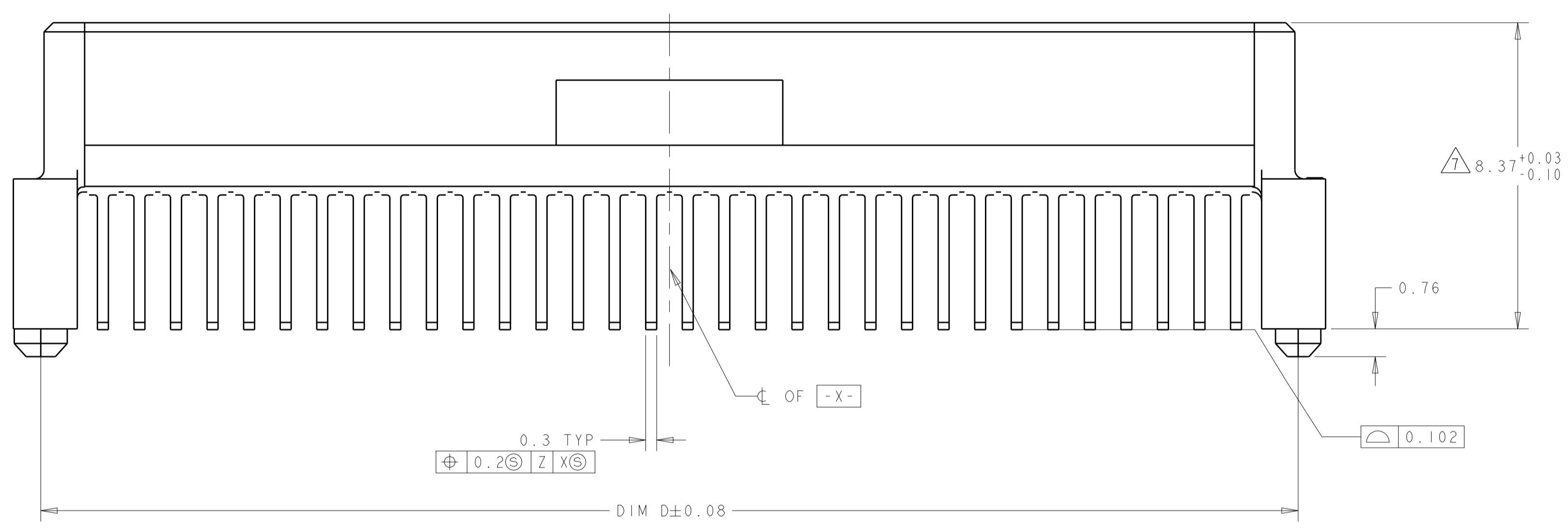
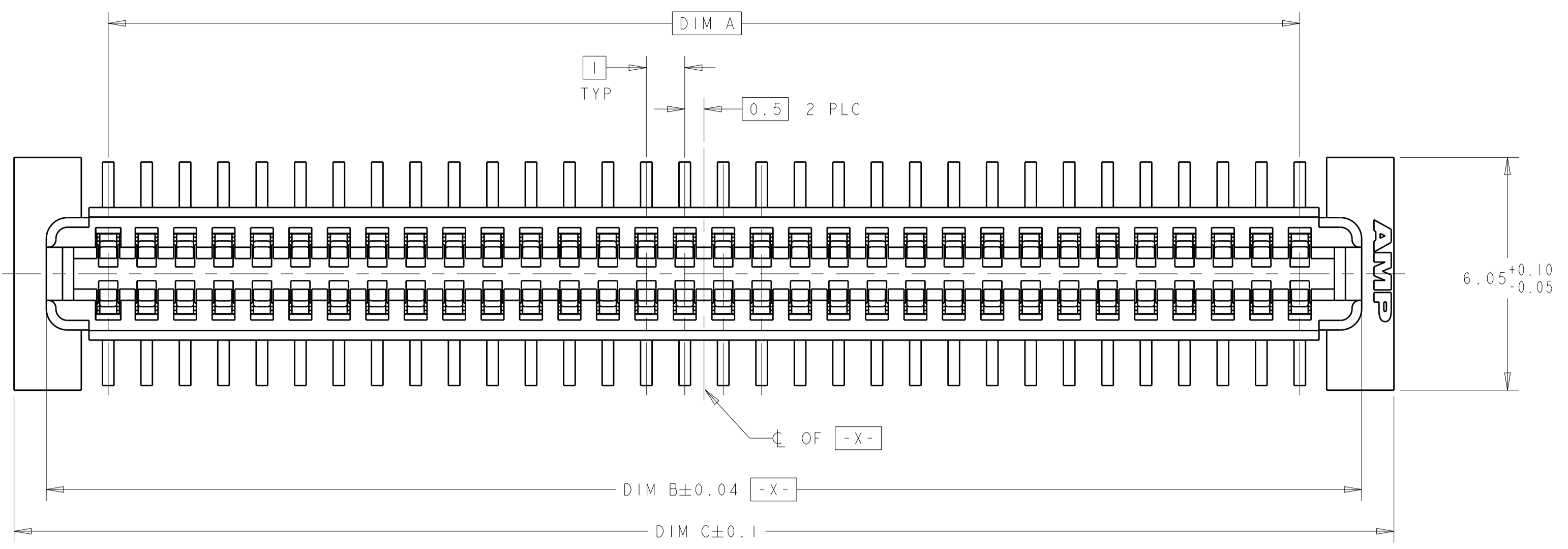
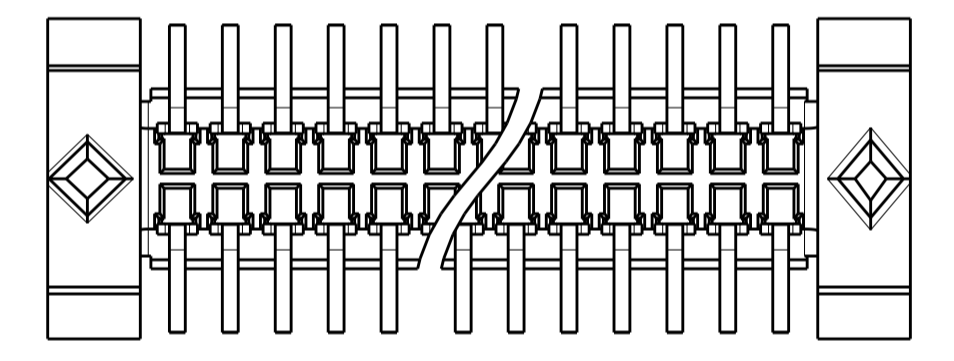


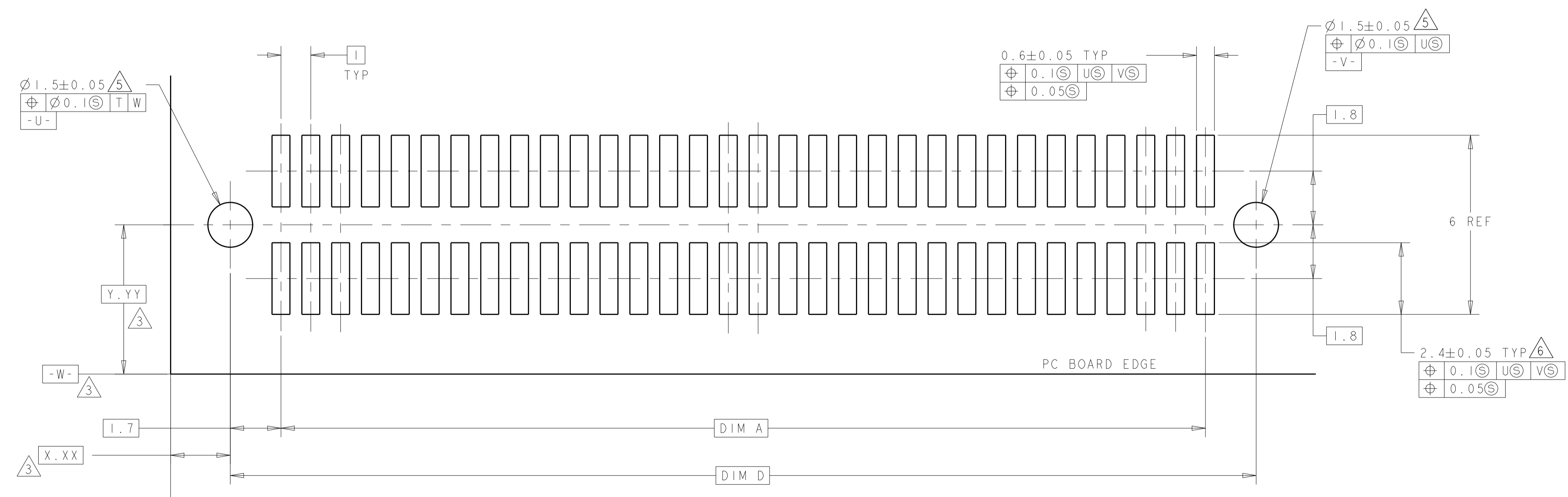
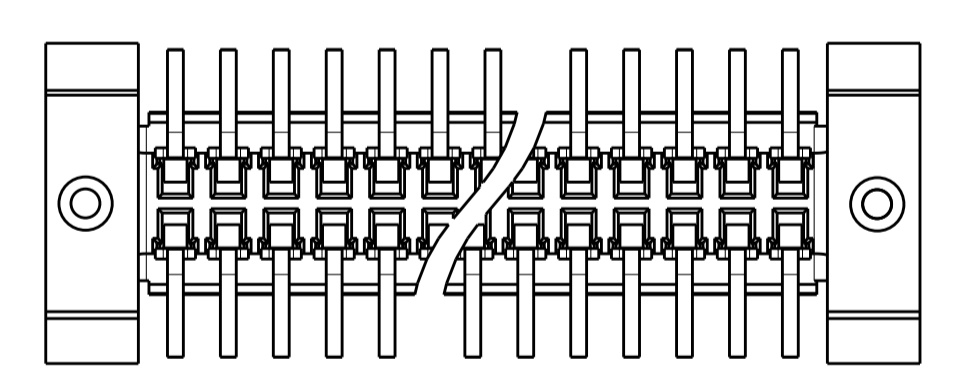
REVISIONS				
P.	LTN.	DESCRIPTION	DATE	OWN. APVD.
J		REVISED PER ECR-14-016951	11FEB2015	J. T. W. H.



STYLE A POST



STYLE B POST



RECOMMENDED PC BOARD LAYOUT

- HOUSING MATERIAL: HIGH TEMPERATURE THERMOPLASTIC, COLOR; BLACK. CONTACT MATERIAL: PHOSPHOR BRONZE.
- CONTACT FINISH: NICKEL UNDERPLATE ALL OVER, MATING SURFACES PLATED TO MEET PLI PERFORMANCE REQUIREMENTS OF INDUSTRY SPECIFICATION EIA-700AAAB, SOLDER TAILS PLATED TIN-LEAD.
- DATUM LOCATIONS AND BASIC DIMENSIONS TO BE ESTABLISHED BY THE CUSTOMER. CONSULT AMP ENGINEERING WHEN PLACING MULTIPLE CONNECTORS ON A PC BOARD.
- PACKAGED IN TAPE ON REEL PER EIA-481.
- 1.5 MIN DIAMETER HOLE SHOULD BE USED IF USING POST STYLE "A" AND PLACING ON PCB WITH VACUUM PLACEMENT EQUIPMENT.
- SHORTER SOLDER LANDS MAY BE USED PER EIA 700AAAB, HOWEVER 2.4 LENGTH ASSURES OPTIMUM SOLDER FILLET REGARDLESS OF MANUFACTURER OF CONNECTOR.
- REFERRED TO AS DIM H = 8.3±0.1 IN EIA 700AAAB SPECIFICATION.
- CONTACT FINISH: 0.002 MINIMUM BRIGHT TIN-LEAD (93-7) ON SOLDER AREA, 0.00127 MINIMUM GOLD ON MATING AREA, BOTH OVER 0.00127 MINIMUM NICKEL ON ENTIRE CONTACT.
- SQUARE AND DIAMOND SHAPED POSTS
- ROUND SHAPED POSTS

POST STYLE	FINISH	DIM D	DIM C	DIM B	DIM A	STACK HGTS	POS	PART NO
8	8	44.4	45.9	44.22	41	13	84	3-120523-2
8	8	34.4	35.9	34.22	31	13	64	3-120523-1
2	2	44.4	45.9	44.22	41	13	84	2-120523-2
2	2	34.4	35.9	34.22	31	13	64	2-120523-1
8	8	44.4	45.9	44.22	41	13	84	1-120523-2
8	8	34.4	35.9	34.22	31	13	64	1-120523-1
2	2	44.4	45.9	44.22	41	13	84	120523-2
2	2	34.4	35.9	34.22	31	13	64	120523-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

AWN: J. REED 27/11/97
CHK: L. VO 27/11/97
APVD: -

TE Connectivity

RCPT ASSY, 1.0mm FH(IEEE1386)
CONNECTOR

PRODUCT SPEC: 502-1079
APPLICATION SPEC: 114-25045

SCALE: 10:1 SHEET: 1 OF 1 REV: J

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)